



2014 Intel Solutions Summit

**SERVER
INNOVATION
AWARD**

Converged cloud Infrastructure increases efficiency and flexibility while reducing power, cooling, and support costs

AMAX wins the 2014 Intel Server innovation Award for bringing an open, converged cloud infrastructure to the data center.



CHALLENGE >

Many data centers build cloud solutions using separate compute, networking, and storage solutions from multiple vendors. The result is different support teams from different vendors, which means potential conflicts with upgrade cycles, technology refreshes, and more. This disparate approach also increases operational costs, and adds unnecessary complexity when troubleshooting technical issues.

SOLUTION >

IO Data Center turned to AMAX for the converged hardware platform on which to build their product, IO.Cloud. AMAX architected the compute, storage, and network components into an open rack based on the most efficient and modular data center building blocks available in Open Compute (OCP) platforms, all managed with OpenStack technology. "We wanted to create a solution where data center managers could not only build their cloud from the ground up, but provide all the components they need under one vendor where the whole solution is integrated," said Julia Shih, Director of Strategic Alliance for AMAX.

A converged infrastructure consolidates the compute, networking, and storage functionality in one integrated solution. The AMAX CloudMax* Converged Cloud Infrastructure solution combines an Intel® technology-based Open Compute hardware platform with IO Data Center's innovative system management software. The resulting IO.Cloud is a converged cloud infrastructure designed to utilize the density, performance, uptime, and scalability benefits of the AMAX CloudMax Converged Cloud Infrastructure.

The system eliminates validation and compatibility issues and reduces the cost of power, cooling and space on the data center floor, which reduces operational expenditures. The IO.Cloud solution was designed to be flexible, letting users quickly and easily configure the system to provide the services they need, when they need it. The modular design provides the ability to easily manage and provision the compute, networking, and storage components in a single interface.

"Basing the design on OCP means the hardware itself is extremely modular and highly efficient," says Shih. "Many of the proprietary systems out there come with extra components, whether or not you want or need them. OCP is a platform that is stripped down to just what's needed specifically to deliver cloud services."

A key benefit to the OCP hardware design is that it is open and modular, which allows users to reconfigure systems to respond to changes in requirements. This gives companies the ultimate in business agility without having to overspend for application-specific servers that may remain idle at various times during usage cycles.

At the 2014 Open Compute Project Summit keynote, George Slessman, CEO of IO.Cloud said, "This is what the data center is going to be for enterprises. The days of cardboard boxes being shipped to data centers, unboxed, put into racks, custom configured, custom cabled, and custom managed is coming to an end." He said the IO.Cloud open solution is "the data center as API," demonstrating the ease of provisioning a server using his smartphone. "Data centers are going to be provisioned with clicks," he said.

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